CnC Tech

Industrial Cable and Connector Technology

CnC Tech Soldering Recommendations for USBs

Recommended temperature and time periods for the soldering process

Series	Soldering Method	Temperature in the furnace (lead-free)	Plastic	Furnace time	Soldering time
1001-001-01000	wave	235°C ± 5°C	PBT	4~6 mins.	5±0.5 sec
1001-002-01100	wave	235°C ± 5°C	LCP	4~6 mins.	5±0.5 sec
	reflow	260°C ± 5°C	LCP	4~6 mins.	5±0.5 sec
1001-003-02000	wave	235°C ± 5°C	PBT	4~6 mins.	5±0.5 sec
1001-004-01010	wave	235°C ± 5°C	PBT	4~6 mins.	5±0.5 sec
1001-007-01020	wave	235°C ± 5°C	PBT	4~6 mins.	5±0.5 sec
1001-008-01001	wave	235°C ± 5°C	PBT	4~6 mins.	5±0.5 sec
1001-008B-01001	wave	235°C ± 5°C	PBT	4~6 mins.	5±0.5 sec
1001-010-01001	wave	235°C ± 5°C	PBT	4~6 mins.	5±0.5 sec
1001-011-01101(-TR)	wave	235°C ± 5°C	LCP	4~6 mins.	5±0.5 sec
	reflow	260°C ± 5°C	LCP	4~6 mins.	5±0.5 sec
1001-012-01001	wave	235°C ± 5°C	PBT	4~6 mins.	5±0.5 sec
1001-012A-01001	wave	235°C ± 5°C	PBT	4~6 mins.	5±0.5 sec
1002-001-01000	wave	235°C ± 5°C	PBT	4~6 mins.	5±0.5 sec
1002-002-01100(-TR)	wave	235°C ± 5°C	LCP	4~6 mins.	5±0.5 sec
	reflow	260°C ± 5°C	LCP	4~6 mins.	5±0.5 sec
1002-003-02000	wave	235°C ± 5°C	PBT	4~6 mins.	5±0.5 sec
1002-004-01010	wave	235°C ± 5°C	PBT	4~6 mins.	5±0.5 sec
1002-005-12100(-1)-TR	wave	235°C ± 5°C	LCP	4~6 mins.	5±0.5 sec
	reflow	260°C ± 5°C	LCP	4~6 mins.	5±0.5 sec
1002-012-01020	wave	235°C ± 5°C	PBT	4~6 mins.	5±0.5 sec
1002-013-01001	wave	235°C ± 5°C	PBT	4~6 mins.	5±0.5 sec
1002-014-01000	wave	235°C ± 5°C	PBT	4~6 mins.	5±0.5 sec
1002-015-01001	wave	235°C ± 5°C	PBT	4~6 mins.	5±0.5 sec
1002-016-01101(-TR)	wave	235°C ± 5°C	LCP	4~6 mins.	5±0.5 sec
	reflow	260°C ± 5°C	LCP	4~6 mins.	5±0.5 sec
1002-021-01000	wave	235°C ± 5°C	PBT	4~6 mins.	5±0.5 sec
1003-001-01000	wave	235°C ± 5°C	PBT	4~6 mins.	5±0.5 sec
1003-001-0100180	wave	235°C ± 5°C	PBT	4~6 mins.	5±0.5 sec
1003-002-01100(-TR)	wave	235°C ± 5°C	LCP	4~6 mins.	5±0.5 sec
	reflow	260°C ± 5°C	LCP	4~6 mins.	5±0.5 sec
1003-004-01010	wave	235°C ± 5°C	PBT	4~6 mins.	5±0.5 sec
1003-005-22100-TR	wave	235°C ± 5°C	LCP	4~6 mins.	5±0.5 sec
	reflow	260°C ± 5°C	LCP	4~6 mins.	5±0.5 sec

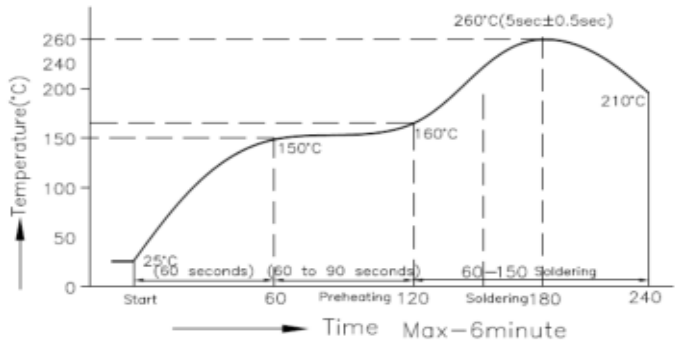
1003-005-23100-TR	wave	235°C ± 5°C	LCP	4~6 mins.	5±0.5 sec
	reflow	260°C ± 5°C	LCP	4~6 mins.	5±0.5 sec
1003-007-01010	wave	235°C ± 5°C	PBT	4~6 mins.	5±0.5 sec
1003-024-02000	wave	235°C ± 5°C	PBT	4~6 mins.	5±0.5 sec

* Applicable for parts with a date code AFTER 20/02

Reflow Soldering

Solderbility Profile

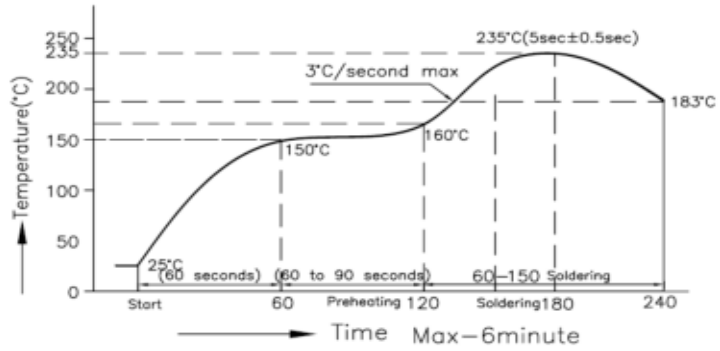
Sub=LCP Material Temperature Specification

Solder regular Condition	1)Soldering temp:260°C±5°C 2)Time:5±0.5 sec 3)Solder wetting percentage:95% min
Reflow Condition	**Test Conditions**
 LCP Recommended Temperature Profile	1)Solder Method: Reflow or Wave 2)Environment: Room air 3)Solder Composition: Soldering Paste 4)Test Board: 52mmX36.5mmX1.6mm thick 5) This temperature profile is based on the above conditions. Individual applications the actual temperature may vary.Consult your solder paste and equipment manufacturer for specific recommendations 6)There must not be visible defect after testing

Wave Soldering

Solderbility Profile

Sub=PBT Material Temperature Specification

Solder regular Condition	1)Soldering temp:235°C±5°C 2)Time:5±0.5 sec 3)Solder wetting percentage:95% min
Wave Condition	**Test Conditions**
 PBT Recommended Temperature Profile	1)Solder Method:Wave -Soldering 2)Environment: Room air 3)Solder Composition: Soldering Paste 4)Test Board: 52mmX36.5mmX1.6mm thick 5) This temperature profile is based on the above conditions. Individual applications the actual temperature may vary.Consult your solder paste and equipment manufacturer for specific recommendations 6)There must not be visible defect after testing